

disposed, and each of said active matrix circuit and said driver circuit comprising thin film transistors provided over said first substrate;

a second substrate opposed to said first substrate;

a liquid crystal provided between said first substrate and said second substrate;

a sealing member provided between said first substrate and said second substrate for sealing said liquid crystal therebetween, said sealing member enclosing said driver circuit;

an inlet for injecting said liquid crystal between said first substrate and said second substrate,

wherein said inlet is provided to said sealing member and on a side edge of said first substrate and said second substrate corresponding to said one side of said first substrate.

62. The device of claim 61 wherein the thin film transistors of each of said active matrix circuit and said driver circuit are formed over said first substrate through a common process.

63. The device of claim 61 wherein said sealing member contains spacers.

64. The device of claim 61 wherein said sealing member comprises an ultraviolet-curable resin.

65. The device of claim 61 wherein said second substrate has at least one side edge which is substantially aligned with a side edge of said first substrate.

66. An active matrix type display device comprising:
a first substrate;
an active matrix circuit having a plurality of pixels arranged in a matrix form over said first substrate;
at least one driver circuit for driving said active matrix circuit over said first

substrate, there being at least one side of said first substrate at which no driver circuit is disposed, and each of said active matrix circuit and said driver circuit comprising thin film transistors provided over said first substrate;

a second substrate opposed to said first substrate;

a liquid crystal provided between said first substrate and said second substrate;

a resin material provided between said first and second substrates, said resin material covering said driver circuit;

a sealing member provided between said first substrate and said second substrate and enclosing said driver circuit; and

an inlet for injecting said liquid crystal between said first substrate and said second substrate,

wherein said inlet is provided to said sealing member and on a side edge of said first substrate and said second substrate corresponding to said one side of said first substrate.

67. The device of claim 66 wherein the thin film transistors of each of said active matrix circuit and said driver circuit are formed over said first substrate through a common process.

68. The device of claim 66 wherein said sealing member contains spacers.

69. The device of claim 66 wherein said sealing member comprises an ultraviolet-curable resin.

70. The device of claim 66 wherein said second substrate has at least one side edge which is substantially aligned with a side edge of said first substrate.--

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